Chip back potential is the level which bulk silicon is maintained by on-chip connection, or it is the level to which the chip back must be connected when specifically stated below. If no potential is given the chip back should be isolated.

**.015”**

**ANODE**

**.010 x .010”**

**.0085”**

**.015”**

**PLANAR CHIP**

**Top Material: Al**

**Backside Material: Au**

**Bond Pad Size: .010 x .010”**

**Backside Potential: CATHODE**

**APPROVED BY: DK DIE SIZE .015” X .015” DATE: 10/21/21**

**MFG: MICROSEMI THICKNESS .0085” P/N: 1N3595**

**DG 10.1.2**

#### Rev B, 7/1